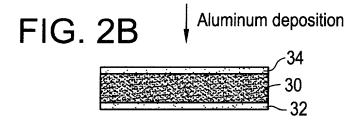


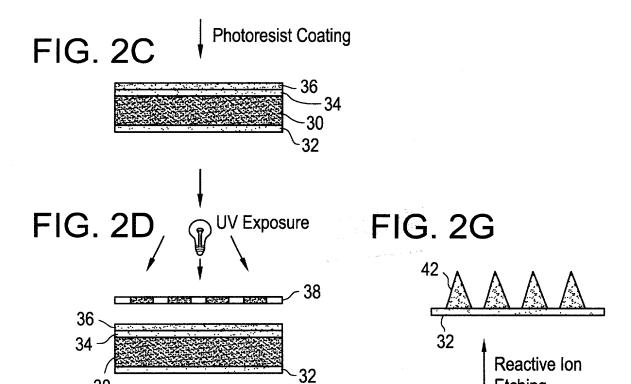
**Etching** 

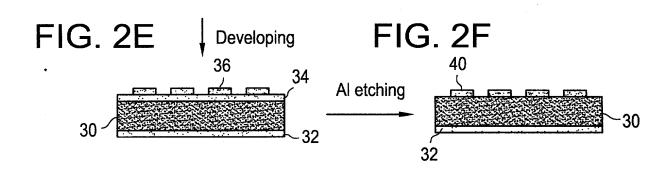
FIG. 2A

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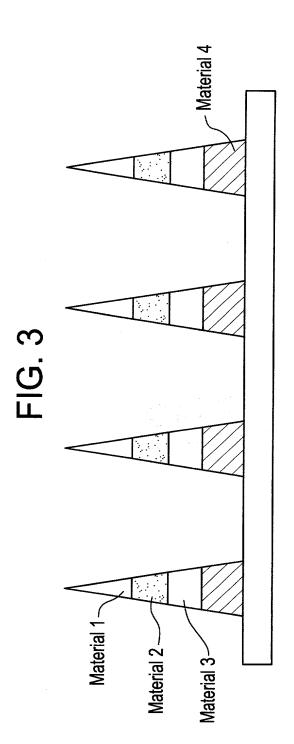
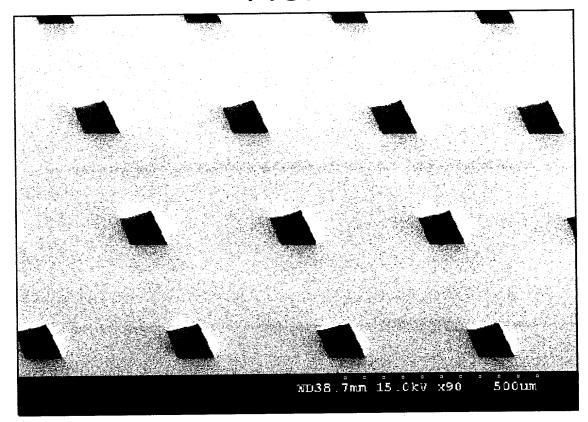


FIG. 4



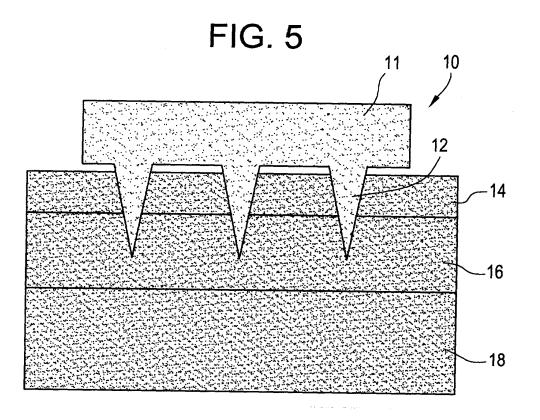
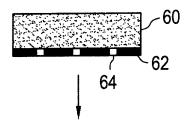
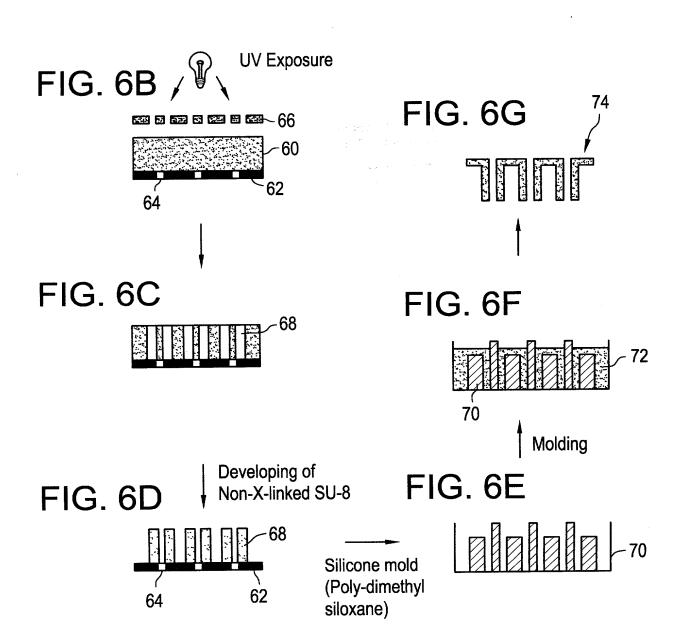
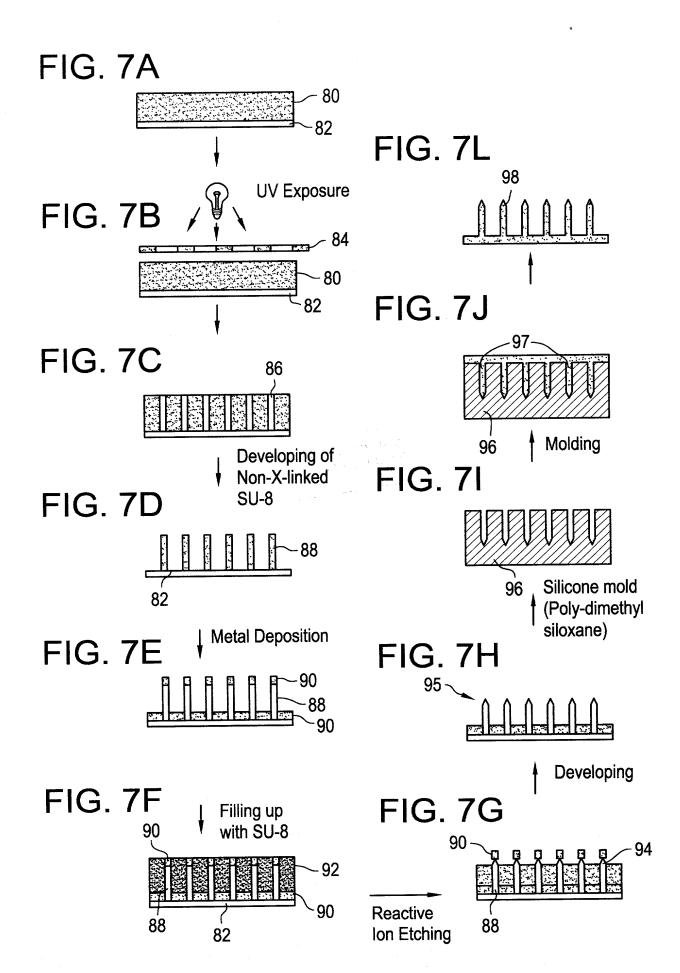


FIG. 6A



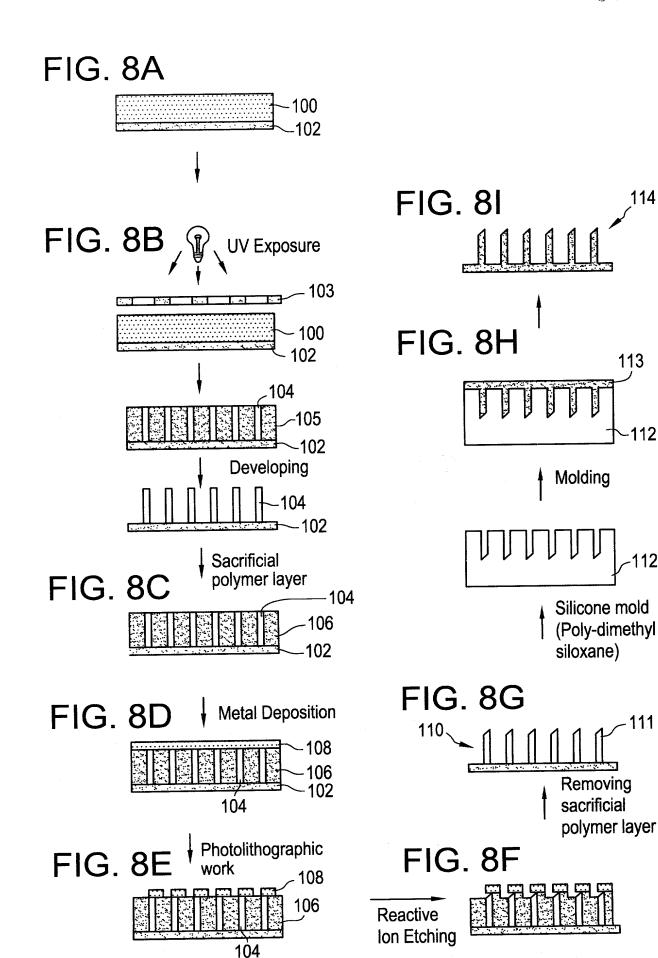




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FIG. 9

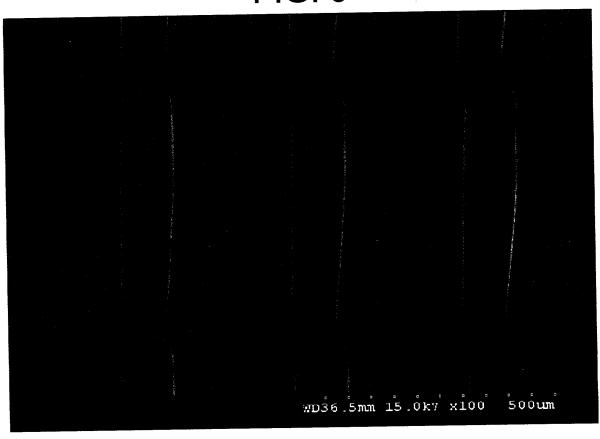


FIG. 10A

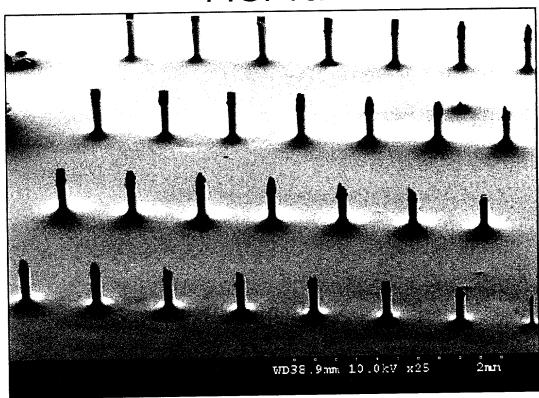


FIG. 10B

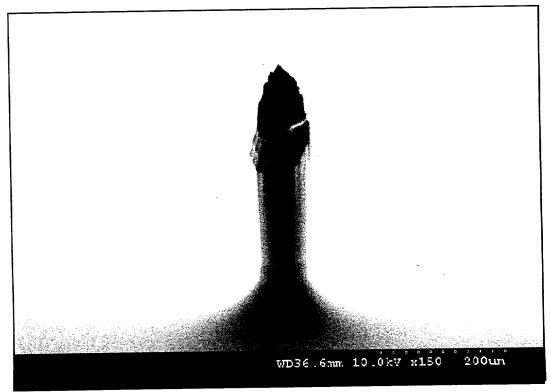
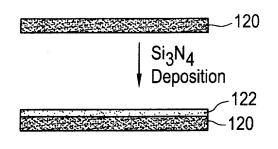


FIG. 11A



Photolithographic work + FIG. 11B Reactive ion etching

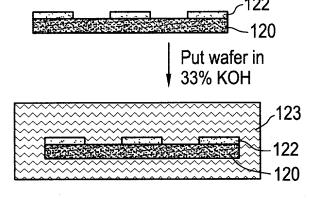
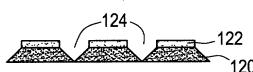
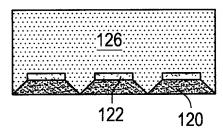


FIG. 11C KOH wet etching



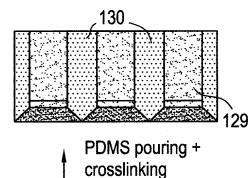
SU-8 epoxy FIG. 11D

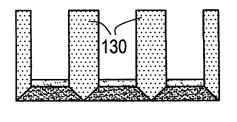


Photolithographic work

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**FIG. 11F** 





Developing

**FIG. 11E** 

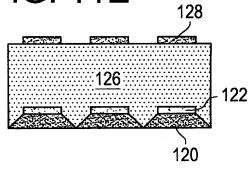


FIG. 12

